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MOUNTING STRUCTURE OF SEMICONDUCTOR DEVICE AND MOUNTING
METHOD OF SEMICONDUCTOR DEVICE

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Abstract:

PURPOSE: To provide a method by which the reliability on the connection is high and which never causes electric conductivity trouble, in case of mounting a semiconductor element on a glass board, with the active face opposite to it. CONSTITUTION: A semiconductor element 1 is loaded on a wiring board 4 where a through hole 9 is opened, and the adhesive for fixing is hardened by heat. Moreover, in case of having used a photosetting adhesive, it can be made the hardening from the rear of the semiconductor device and the hardening from the rear of the glass board. This way, by having opened a through hole, the adhesive can be escaped to outside, so it does not give stress to the connection. Moreover, even if trouble should be found, the semiconductor device could be removed simply from the glass wiring board.

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Mounting structure and mounting process from semiconductor devices

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Thermosetting resin compositions